

Product End-of-Life Disassembly Instructions

Product Type/Category: Notebook

Product Name/Model: APD Nomada

- Purpose:** This document is intended for use by end-of-life (EOL) recyclers, reusers or treatment facilities. It provides the basic instructions for the disassembly of APD products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).
- Compliance:** EU directive 2012/19/EU WEEE - Annex VII materials.

EU directive 2012/19/EU WEEE - Annex VII materials		
Content (Yes/No)	Component	Quantity of components
Polychlorinated biphenyls (PCB) containing capacitors in accordance with Council Directive 96/59/EC of 16 September 1996 on the disposal of polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT)		
No		
Mercury containing components, such as switches or backlighting lamps		
No		
Batteries		
Yes	Lithium-ion Battery	2
Printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimeters		
Yes	Main Printed Circuit Board I/O PCB Touchpad Module Storage Drive (SSD) RAM Module T-con Board	6
Toner cartridges, liquid and paste, as well as colour toner		
No		
Plastic containing brominated flame retardants (not including PCB/PCA already listed as a separate item above)		
No		
Asbestos waste and components which contain asbestos		
No		
Cathode ray tubes		
No		

Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		
No		
Gas discharge lamps		
No		
Liquid crystal displays (together with their casing where appropriate) of a surface greater than 100 square centimetres and all those back-lighted with gas discharge lamps		
Yes	Liquid Crystal Display (LCD) screen	1
External electric cables		
Yes	Power Cords Adapter	2
Components containing refractory ceramic fibres as described in Commission Directive 97/69/EC of 5 December 1997 adapting to technical progress for the 23rd time Council Directive 67/548/EEC on the approximation of the laws, regulations and administrative provisions relating to the classification, packaging and labelling of dangerous substances		
No		
Components containing radioactive substances with the exception of components that are below the exemption thresholds set in Article 3 of and Annex I to Council Directive 96/29/Euratom of 13 May 1996 laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionizing radiation		
No		
Electrolyte capacitors containing substances of concern (height > 25 mm, diameter > 25 mm or proportionately similar volume)		
No		

3. **Tools required:** List of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Type/size (if applicable)	Quantity
Screwdriver	Philips PH0	1
Plastic spudger		1
Tweezers		1

4. **Product Disassembly Process:** List of the steps that should be followed to remove components and materials requiring selective treatment. These steps are a general guide and may vary slightly depending on the specific laptop model.

Step	Activity	Description
1	Work area preparation	Set up a clean, well-lit workspace. A non-conductive work area is recommended.

2	Tools preparation	Gather the necessary tools: a screwdriver, a plastic spudger, and tweezers
3	Remove the Bottom Case	Unscrew all the screws holding the bottom case in place. Carefully pry off the bottom case, using a plastic spudger to avoid damaging any clips.
4	Remove the Li-ion Battery	Locate and disconnect the battery connector. Remove the screws securing the battery and carefully lift it out.
5	Remove the Storage Drive (SSD)	Unscrew the drive bay and gently slide out the storage drive.
6	Remove the RAM Module(s)	Release the retention clips on the RAM module(s) and carefully remove it/them.
7	Remove the Cooling Fan	Disconnect the fan's power connector. Remove the screws securing the fan and carefully lift it out.
8	Remove the Wireless Module	Disconnect the wireless module's antenna cables. Remove the screw holding the module in place and carefully remove it.
9	Remove the Speakers	Disconnect all cables and connectors attached to the motherboard. Carefully lift the speakers out.
10	Remove the Main Printed Circuit Board (PCB)	Remove the screws securing the motherboard and carefully lift it out.
11	Remove the I/O PCB	Disconnect all cables and connectors attached to the board. Remove the screws securing the I/O PCB and carefully lift it out.
12	Remove the Touchpad Module	Disconnect the touchpad's data cable. Remove securing the touchpad module and carefully lift it out.
13	Remove the LCD screen	Remove the PCB hinge screws. Release the retention clips on the LCD bezel, carefully remove the LCD screen in place, and carefully lift it out. Remove the LCD hinge screws.
14	Remove the Camera Board	Lift out and gently remove the camera board on top of the screen.
15	Remove the T-con Board	Carefully disconnect any cables attached to the T-con board. Use a plastic spudger to gently lift connectors. Remove the screws that secure the T-con board. Gently lift the T-con board from its mounting position.

Remember: Always handle components and materials with care to avoid damage.

- Product Disassembly Graphic Process:** If the disassembly process is complex, follow the illustrations below to identify the components contained in the product that require selective treatment.

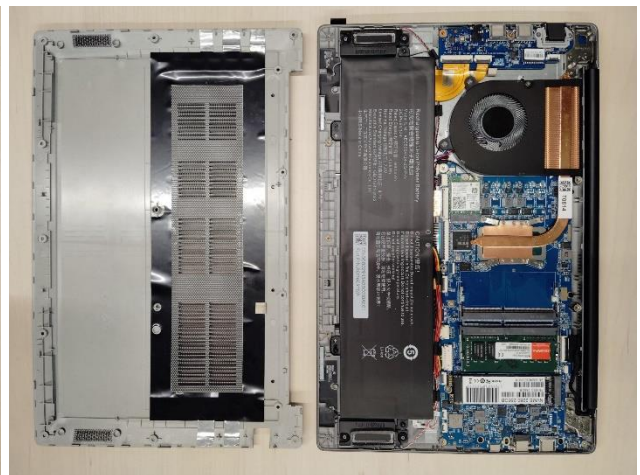
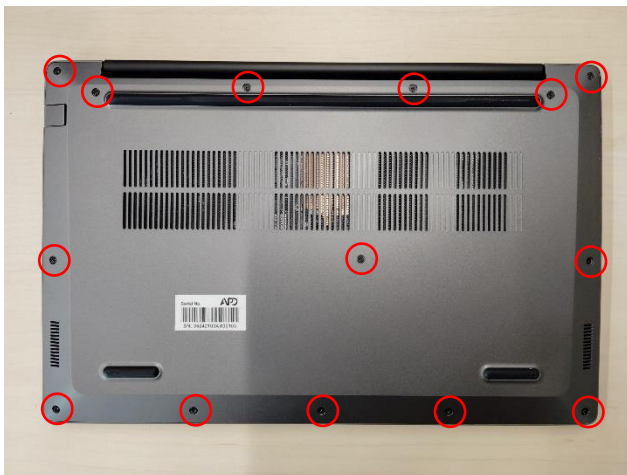
Step 1. Work area preparation



Step 2. Tools preparation



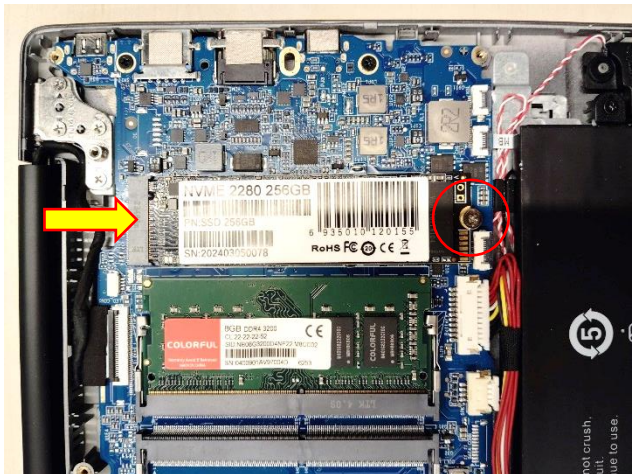
Step 3. Remove the Bottom Case



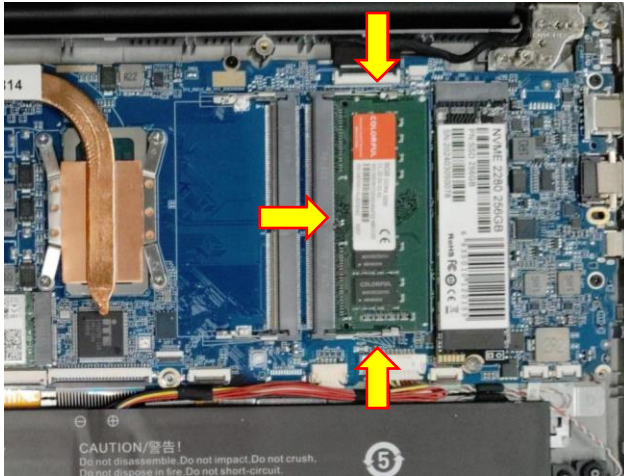
Step 4. Disconnect the Li-ion Battery



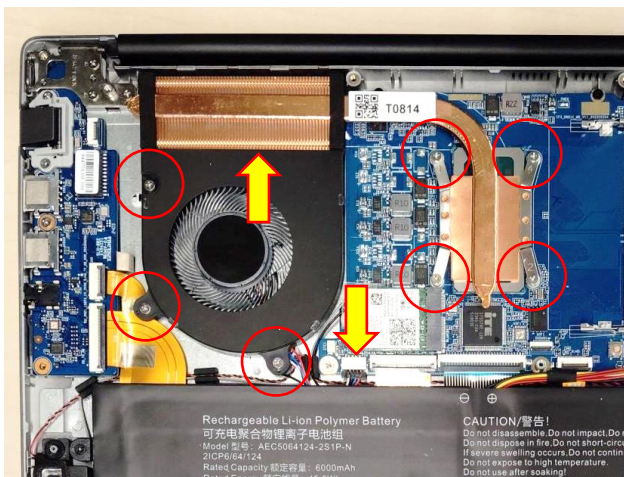
Step 5. Remove the Storage Drive (SSD)



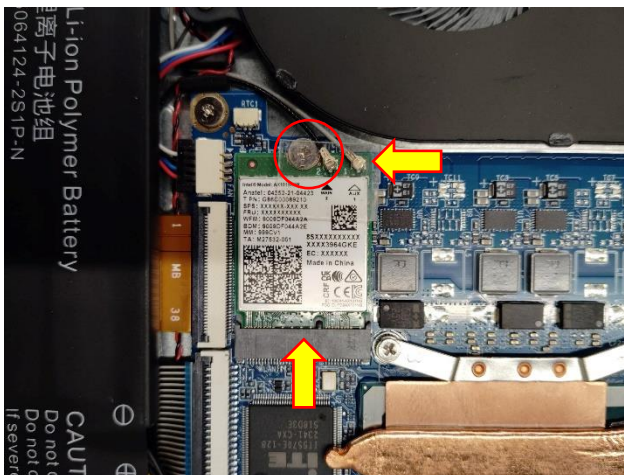
Step 6. Remove the RAM Module(s)



Step 7. Remove the Cooling Fan



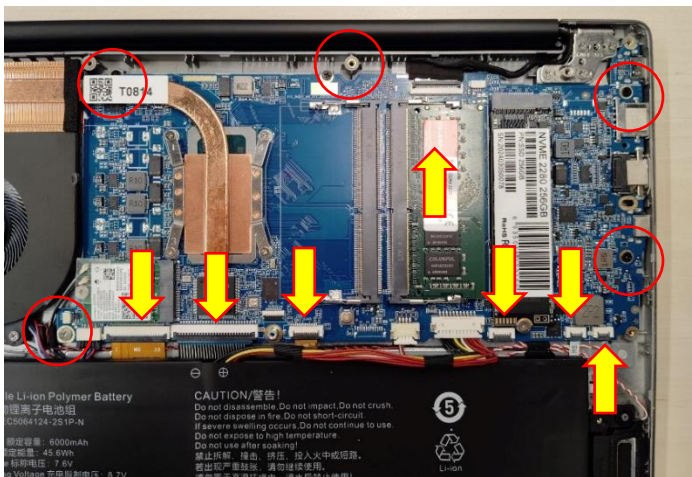
Step 8. Remove the Wireless Module



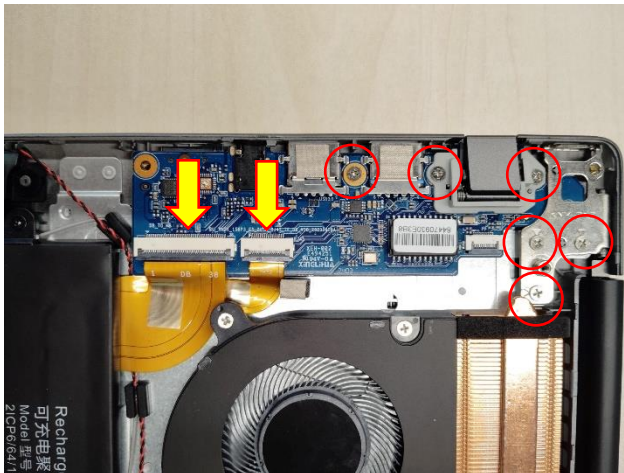
Step 9. Remove the Speakers



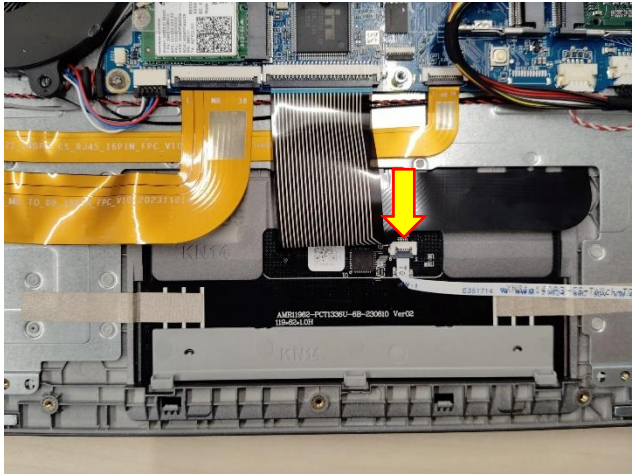
Step 10. Remove the Main Printed Circuit Board (PCB)



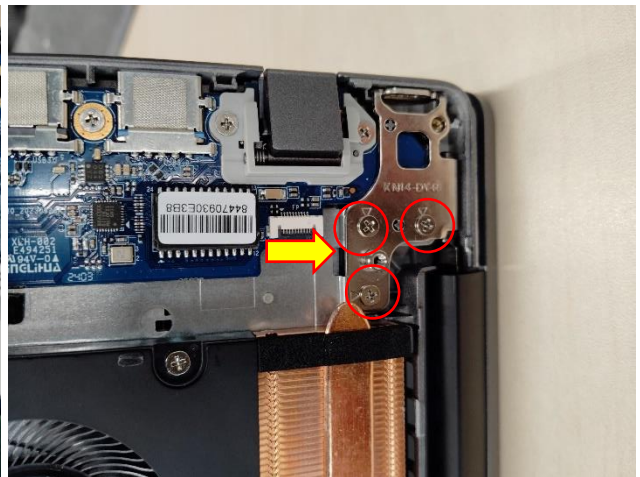
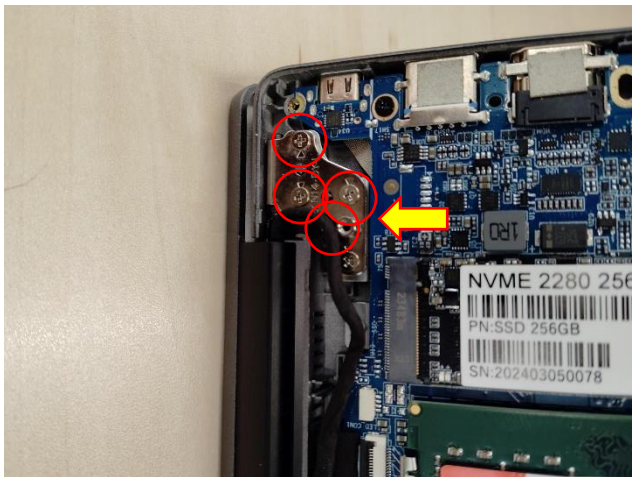
Step 11. Remove the I/O PCB



Step 12. Remove the Touchpad Module



Step 13. Remove the LCD screen



Step 14. Remove the Camera Board



Step 15. Remove the T-con Board

